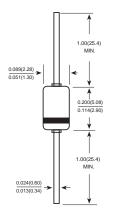
DB₃

BIDIRECTIONAL TRIGGER DIODE

Reverse Voltage - 32 Volts Power: 150mW

DO-35(GLASS)



Dimensions in inches and (millimeters)

FEATURES

- ◆ Small glass structure ensures high reliability
- VBO:28-36V version
- Low breakover current
- High temperature soldering guaranteed 260°C/10 seconds,0.375"(9.5mm) lead length, 5 lbs. (2.3kg) tension

MECHANICAL DATA

Case: JEDEC DO-35 glass body

Terminals: Plated axial leads, solderable per MIL-STD-750,

Method 2026 **Mounting Position**: Any

Weight: 0.005 ounce, 0.14gram

MAXIMUM RATINGS AND CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

	TEST CONDITION	SYMBOLS	VALUE			
			Min.	Тур.	Max.	UNITS
Breakover voltage *	C=22nF **	Vво	28	32	36	VOLTS
Breakover voltage symmetry	C=22nF **	I+VвоI-I-Vво I	-3		3	VOLTS
Dynamic breakover voltage *	(NOTE 1)	IΔV±I	5			VOLTS
Output voltage *	DIAGRAM2	Vo	5			VOLTS
Breakover current *	C=22nF **	Іво			100	μΑ
Rise time *	DIAGRAM3	tr		1.5		μS
Leakage current *	Vr=0.5Vво	Ів			10	μА
Power dissipation on printed circuit	T _A =65℃	Pd			150	mW
Repetitive peak on-state current	tp=20μs f=100Hz	İtrm			2	А
Thermal Resistances from Junction to ambient		R⊕ja			400	°C/W
Thermal Resistances from Junction to lead		R⊖JL			150	
Operating junction and storage temperature range		ТЈ,Тѕтс	-40		125	°C

 ^{* :}Electrical characteristic appoicaboe in forward and reverse directions.

Note 1:lso from lso to 10mA



^{** :}Connected in parallel with the devices.

RATINGS AND CHARACTERISTIC CURVES DB3

DIAGRAM 1:CURRENT-VOLTAGE CHARACTERISTICS

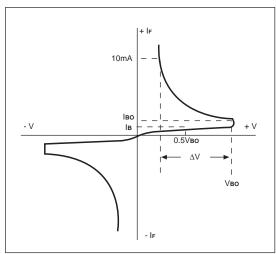


DIAGRAM 2:TEST CIRCUIT OUTPUT VOLTAGE

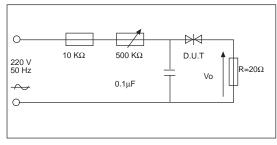


DIAGRAM 3:TEST CIRCUIT SEE DIAGRAM 2.ADJUST R FOR IP=0.5A

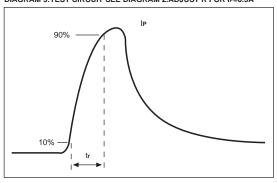


FIG. 1-POWER DISSIPATION VERSUS AMBIENT TEMPERATURE(MAXIMUM VALUES)

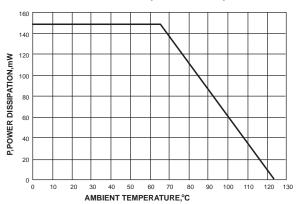


FIG. 2-PEAK PULSE CURRENT VERSUS PULSE DURATION (MAXIMUM VALUES)

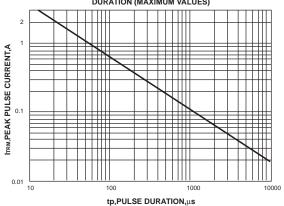


FIG. 3-RELATIVE VARIATION OF VBO VERSUS JUNCTION TEMPERATURE(TYPICAL VALUES)

